

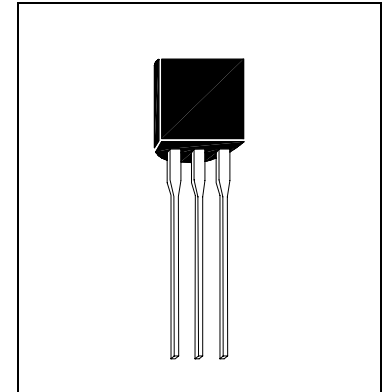


HE8050S

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HE8050S is designed for general purpose amplifier applications.



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage 25 V
 VCEO Collector to Emitter Voltage 20 V
 VEBO Emitter to Base Voltage 5 V
 IC Collector Current 700 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	25	-	-	V	IC=10uA, IE=0
BVCEO	20	-	-	V	IC=1mA, IB=0
VEBO	5	-	-	V	IE=10uA, IC=0
ICBO	-	-	1	uA	VCB=20V, IE=0
IEBO	-	-	100	nA	VEB=5V, IC=0
*VCE(sat)	-	-	0.5	V	IC=0.5A, IB=50mA
VBE(on)	-	-	1	V	VCE=1V, IC=150mA
*hFE1	100	-	500		VCE=1V, IC=150mA
*hFE2	-	140	-		VCE=1V, IC=500mA
fT	150	-	-	MHz	VCE=10V, IC=20mA, f=100MHz
Cob	-	-	10	pF	VCB=10V, f=1MHz, IE=0

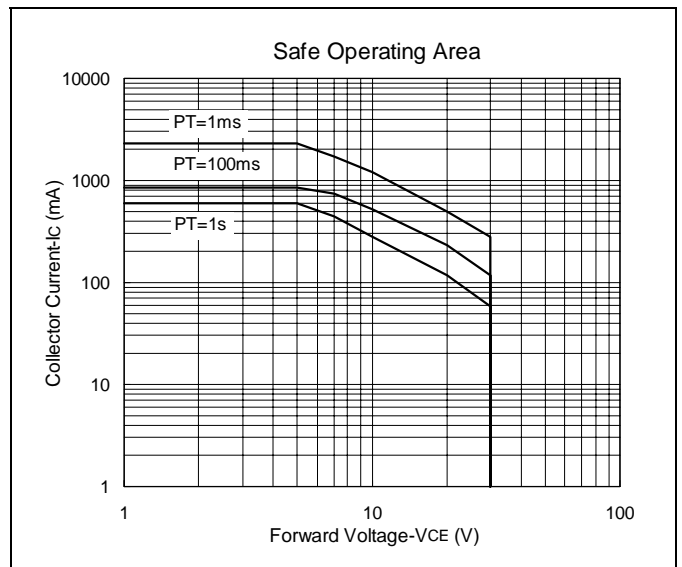
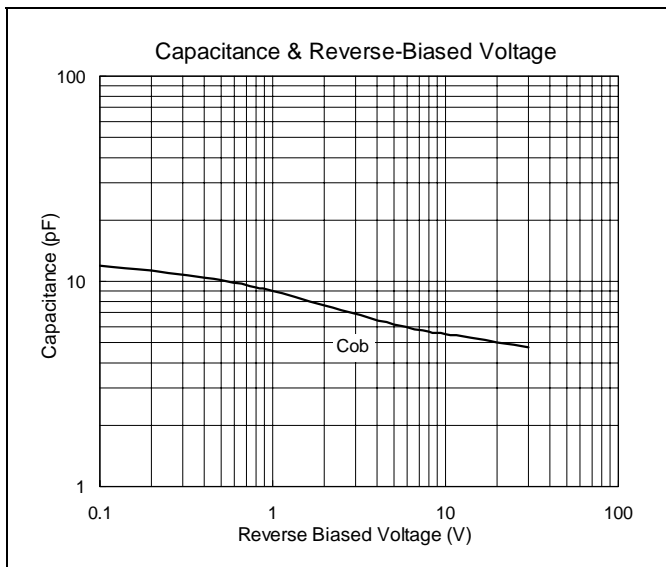
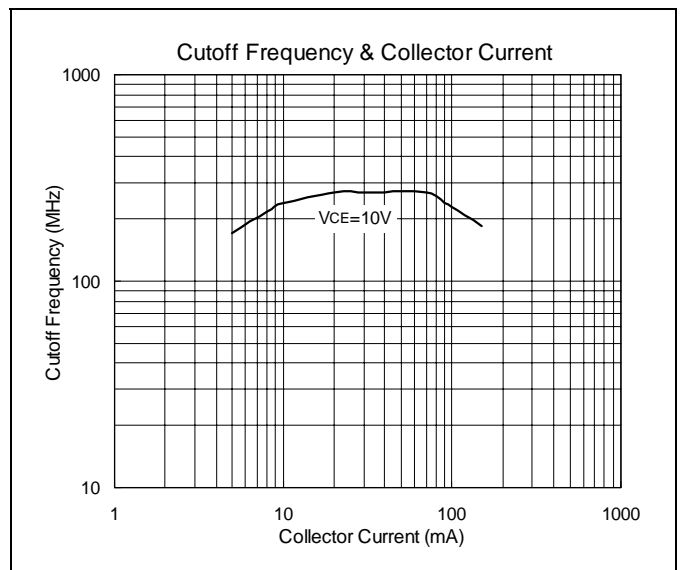
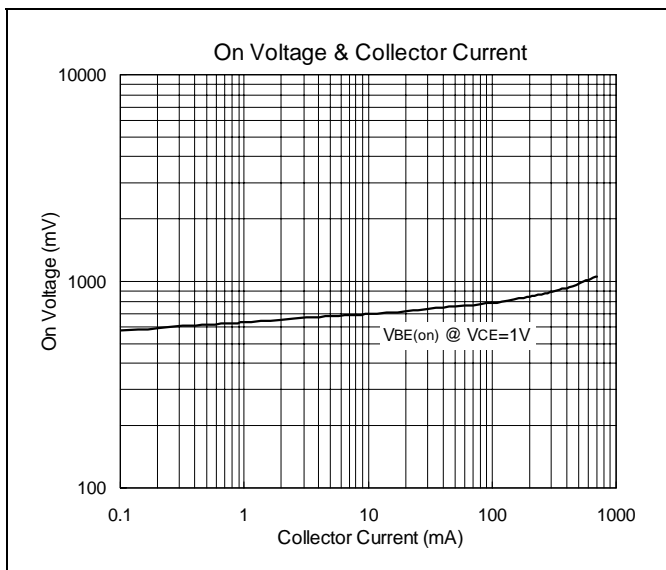
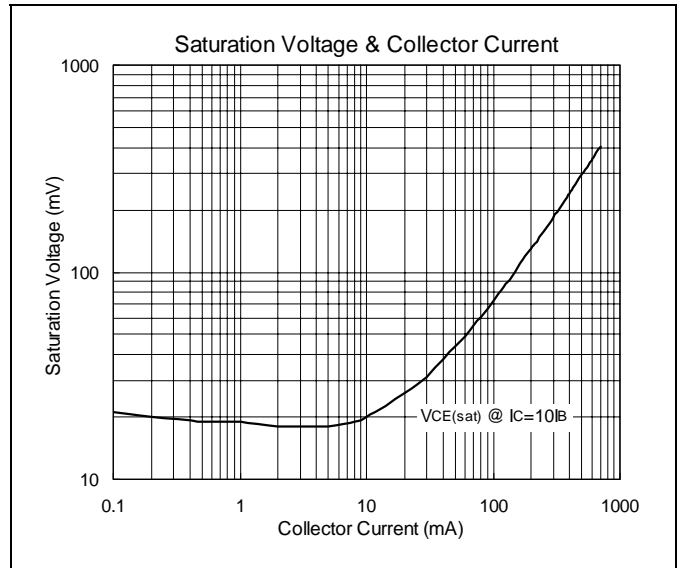
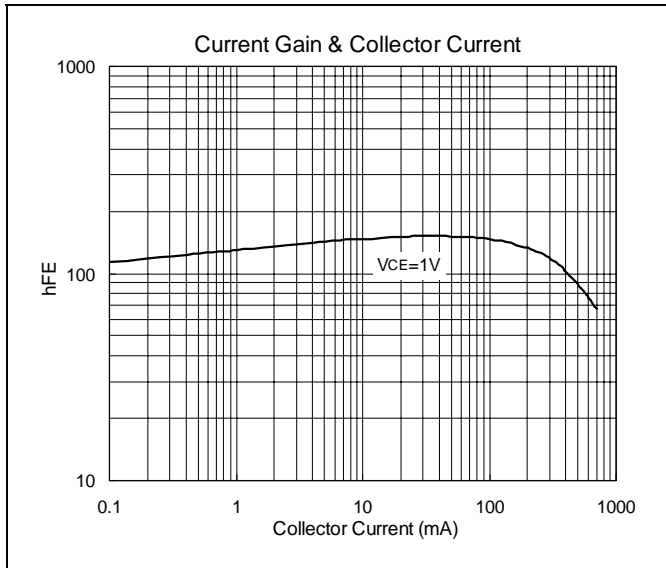
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

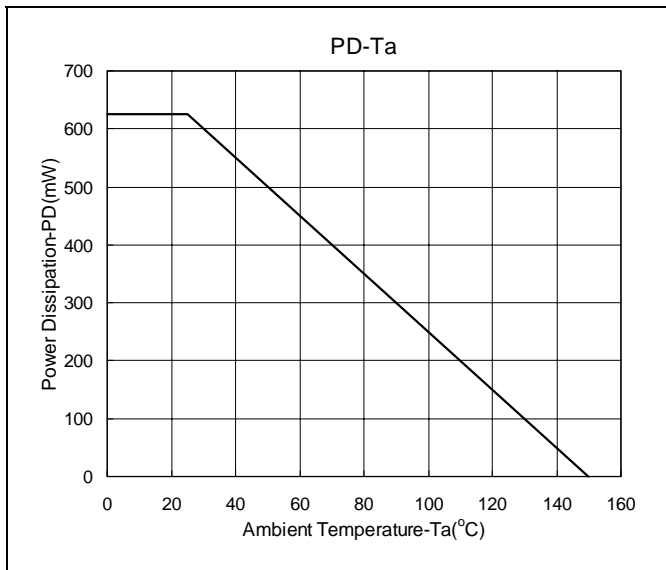
Classifications of hFE

Rank	C	C1	D	D1	E
hFE1	100-180	100-180	160-300	160-300	250-500
hFE2	-	>50	-	>50	-



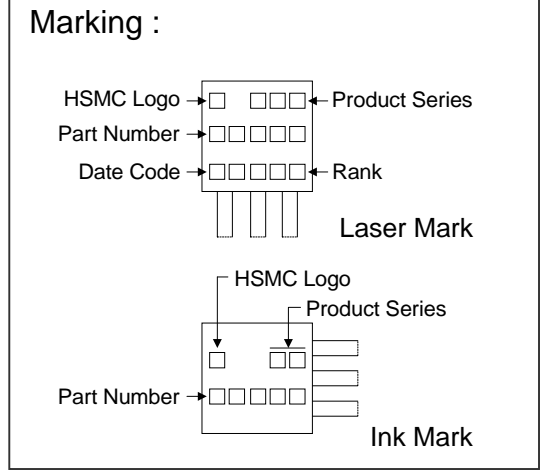
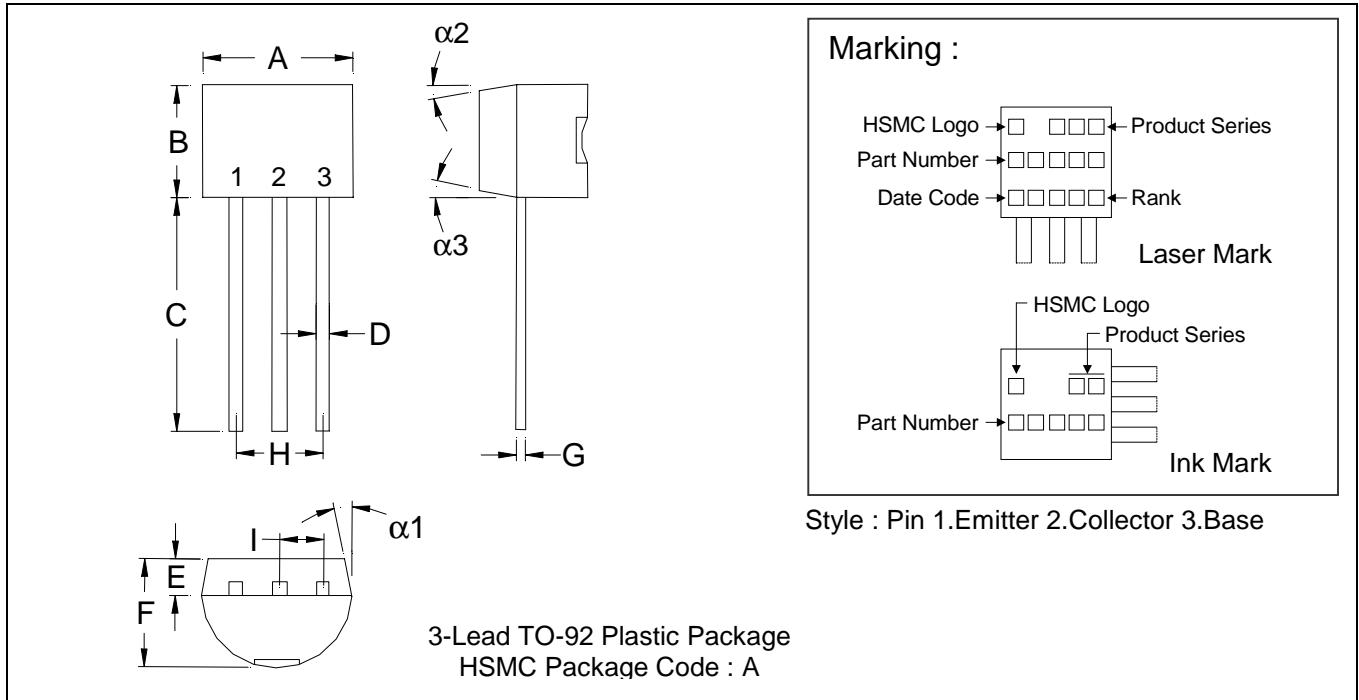
Characteristics Curve







TO-92 Dimension



Style : Pin 1. Emitter 2. Collector 3. Base

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes :**
- 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 - 2.Controlling dimension : millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5983621~5 Fax : 886-3-5982931



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